

APPLICABLE STANDARD				
RATING	VOLTAGE	1 5 0 V AC	CURRENT	1 A
	OPERATING TEMPERATURE RANGE	-35°C TO +85 °C (NOTES 1)	STORAGE TEMPERATURE RANGE	-10°C TO +60°C (NOTE3)
	OPERATING HUMIDITY RANGE	20 % TO 80 % (NOTES 2)	STORAGE HUMIDITY RANGE	40 % TO 70 % (NOTE3)
	APPLICABLE CONNECTOR	DF13-*S-1. 25C	APPLICABLE CONTACT	DF13-2630SCFA, DF13-3032SCFA

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
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CONSTRUCTION

GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	X	X
MARKING	CONFIRMED VISUALLY.		X	X

ELECTRIC CHARACTERISTICS

CONTACT RESISTANCE	100 mA (DC OR 1000 Hz).	30 mΩ MAX.	X	-
INSULATION RESISTANCE	100 V DC.	500 MΩ MIN.	X	-
VOLTAGE PROOF	500 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	X	-

MECHANICAL CHARACTERISTICS

MECHANICAL OPERATION	50 TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
SHOCK	490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		X	-

ENVIRONMENTAL CHARACTERISTICS

RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55 → 5 TO 35 → +85 → 5 TO 35 °C TIME 30 → 5 MAX → 30 → 5 MAX min UNDER 5 CYCLES.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	-
DAMP HEAT (STEADY STATE)	EXPOSED AT 40 ± 2 °C, 90 TO 95 %, 96 h.		X	-
RESISTANCE TO SOLDERING HEAT	1) REFLOW SOLDERING ◀REFLOW AREA▶ MAX240°C WITHIN 10 sec MIN 220°C 10sec to 30 sec ◀PREHEATING AREA▶ 140°C to 160°C 60 sec to 120 sec PUT THROUGH IN REFLOW FUMACE TWICE LEAVE IN AMBIENT TEMPERATURE AND HUMIDITY FOR 1 HOUR. CONNECTOR TEMPERATURE TO BE AMBIENT FOR SECOND REFLOW. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE :290 ± 10°C, SOLDERING TIME : 3sec. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	-
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 230 ± 3°C FOR INSERTION DURATION, 3sec.	SOLDER SHALL COVER A MINIMUM OF 95% OF THE SURFACE BEING IMMersed.	X	-

REMARKS

NOTE1: INCLUDE THE TEMPERATURE RISING BY CURRENT

NOTE2:NO CONDENSING

NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFOR PCB ON BOARD.

AFTER PCB BOARD , OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION

Unless otherwise specified, refer to JIS C 5402.

COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
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	APPROVED	TY.OMA	05.03.16
	CHECKED	HK.UMEHARA	05.03.15
	DESIGNED	TS.KUMAZAWA	05.03.11
	DRAWN	TS.KUMAZAWA	05.03.11

Note	QT:Qualification Test AT:Assurance Test X:Applicable Test	DRAWING NO.	ELC4-083662-02
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	SPECIFICATION SHEET	PART NO.	DF13-*P-1. 25H (50)
	HIROSE ELECTRIC CO., LTD.	CODE NO.	△ 1/1